

Abstract

An embodiment of the present invention provides a novel method which makes LVR to HVR registration possible by wrapping the X and Y scribes around each instance of each layer on both the LVR and HVR reticles; standard HVR
5 reticles and LVR reticles will not align to one another due to registration and electrical test structures in the scribe being in different locations. Another embodiment of the present invention addresses the loss of die per wafer due to increased scribe area when using LVR and HVR reticles in the same set.